

Characteristics

Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified)

Symbol	Parameter			Value	Unit
V_{RRM}	Repetitive peak reverse voltage			60	٧
1	Average femiliard current 5 = 0.5 equare wave	SMA	T _L = 130 °C	4	^
$I_{F(AV)}$ Average forward current, δ = 0.5, square wave	SMA Flat Notch, SMB	T _L = 135 °C	1	Α	
l	Curso non repetitive femurard current	SMA, SMB	$t_{\rm p}$ = 10 ms sinusoidal	75	Α
IFSM	Surge non repetitive forward current	SMA Flat Notch	t _p = 10 ms sinusoidai	100	^
P_{ARM}	Repetitive peak avalanche power t_p = 10 μ s, T_j = 125 $^{\circ}$ C			180	W
T _{stg}	Storage temperature range			-65 to +150	°C
Tj	Maximum operating junction temperature ⁽¹⁾			+150	°C

^{1.} $(dP_{tot}/dT_i) < (1/R_{th(i-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal resistance parameter

Symbol	Parameter	Max. value	Unit	
R _{th(j-I)}		SMA	30 20	
	Junction to lead	SMA Flat Notch		°C/W
		SMB	23	

For more information, please refer to the following application note:

AN5088: Rectifiers thermal management, handling and mounting recommendations

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I_ (1)		T _j = 25 °C	$V_R = V_{RRM}$	-		4	μA
I _R ⁽¹⁾	Reverse leakage current	T _j = 125 °C		-	1.1	4	mA
		T _j = 25 °C	1 - 1 0	-		0.67	
V (2)	Conversed welltographics	$T_{j} = 125 ^{\circ}\text{C}$ $T_{j} = 25 ^{\circ}\text{C}$ $T_{j} = 125 ^{\circ}\text{C}$ $I_{F} = 2 ^{\circ}\text{A}$	-	0.49	0.57		
V _F ⁽²⁾	Forward voltage drop		-		0.8	V	
				-	0.58	0.65	

- 1. Pulse test: $t_p = 5$ ms, $\delta < 2\%$
- 2. Pulse test: $t_p = 380 \ \mu s, \ \delta < 2\%$

To evaluate the conduction losses, use the following equation:

 $P = 0.49 \times I_{F(AV)} + 0.08 \times I_{F^{2}(RMS)}$

For more information, please refer to the following application notes related to the power losses :

- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

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1.1 Characteristics (curves)

Figure 1. Average forward power dissipation versus average forward current $P_{F(AV)}(W)$ 0.7 δ= 0.2 δ= 0.5 δ= 0.1 _ δ= 0.05 0.6 δ= 1 0.5 0.4 0.3 0.2 $I_{F(AV)}(A)$ δ=tp/T 0.0 0.2 0.4 0.8 1.0

Figure 2. Average forward current versus ambient temperature (δ = 0.5)

Figure 3. Normalized avalanche power derating versus pulse duration ($T_i = 125$ °C)

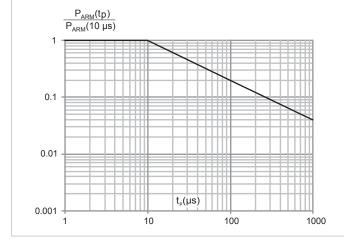


Figure 4. Relative variation of thermal impedance junction to ambient versus pulse duration (SMB)

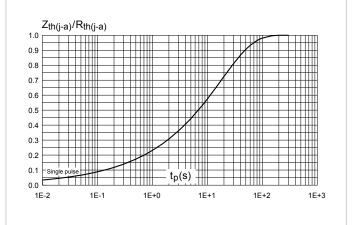


Figure 5. Relative variation of thermal impedance junction to ambient versus pulse duration (SMA)

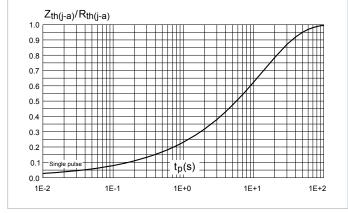
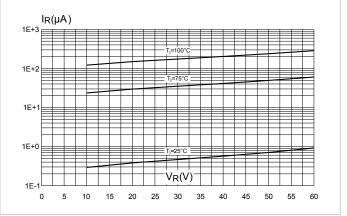


Figure 6. Reverse leakage current versus reverse voltage applied (typical values)



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Figure 7. Junction capacitance versus reverse voltage applied (typical values)

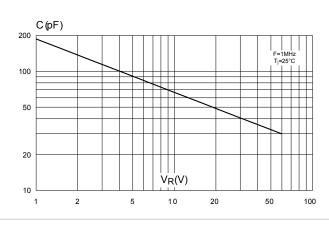


Figure 8. Forward voltage drop versus forward current (maximum values)

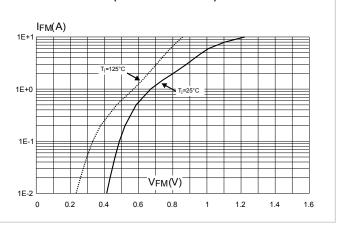


Figure 9. Thermal resistance junction to ambient versus copper surface under each lead (SMB)

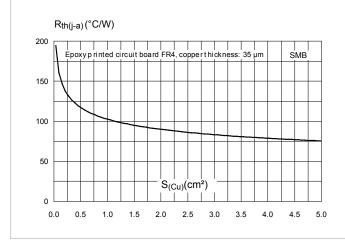


Figure 10. Thermal resistance junction to ambient versus copper surface under each lead (SMA)

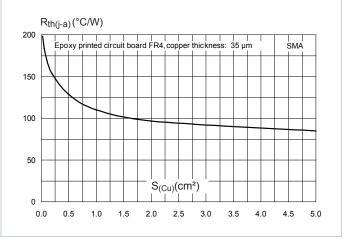
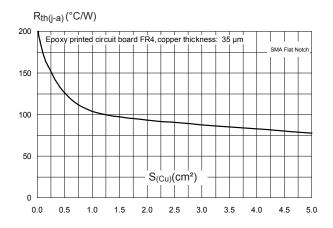


Figure 11. Thermal resistance junction to ambient versus copper surface under each lead (SMA Flat Notch)



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Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 SMA package information

- Epoxy meets UL94, V0
- Cooling method : by conduction (C)

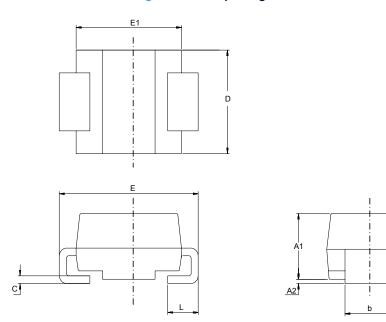


Figure 12. SMA package outline

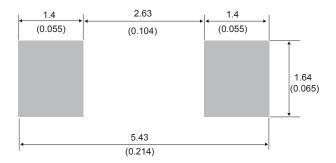
Table 4. SMA package mechanical data

	Dimensions					
Ref.	Millimeters		Inches (for reference only)			
	Min.	Max.	Min.	Max.		
A1	1.90	2.45	0.074	0.097		
A2	0.05	0.20	0.001	0.008		
b	1.25	1.65	0.049	0.065		
С	0.15	0.40	0.005	0.016		
D	2.25	2.90	0.088	0.115		
E	4.80	5.35	0.188	0.211		
E1	3.95	4.60	0.155	0.182		
L	0.75	1.50	0.029	0.060		

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Figure 13. SMA recommended footprint in mm (inches)



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2.2 SMA Flat Notch package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- · Band indicates cathode

Figure 14. SMA Flat Notch package outline

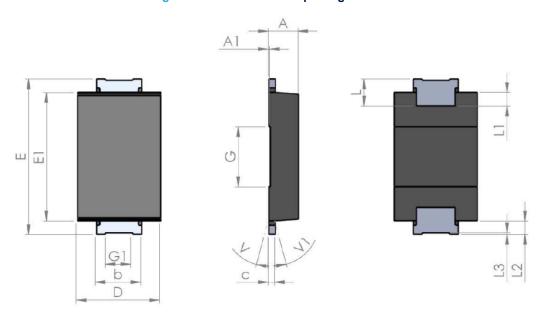


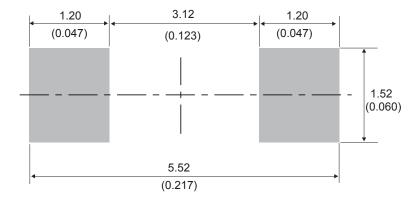
Table 5. SMA Flat Notch package mechanical data

			Dime	ensions		
Ref.		Millimeters		Inch	es (for reference	only)
	Min.	Тур.	Max.	Min.	Тур.	Max.
A1	0.90		1.10	0.035		0.044
A1		0.05			0.002	
b	1.25		1.65	0.049		0.065
С	0.15		0.40	0.005		0.016
D	2.25		2.90	0.088		0.115
E	5.00		5.35	0.196		0.211
E1	3.95		4.60	0.155		0.182
G		2.00			0.079	
G1		0.85			0.033	
L	0.75		1.20	0.029		
L1		0.45			0.018	
L2		0.45			0.018	
L3		0.05			0.002	
V			8°			8°
V1			8°			8°

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Figure 15. SMA Flat Notch recommended footprint in mm (inches)



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2.3 SMB package information

- Epoxy meets UL94, V0
- Lead-free package

Figure 16. SMB package outline

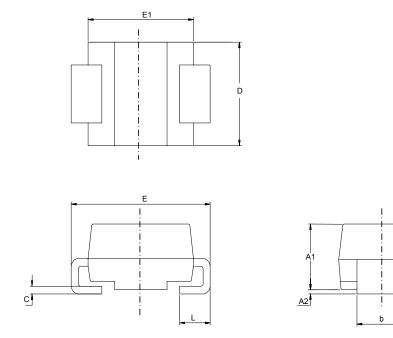


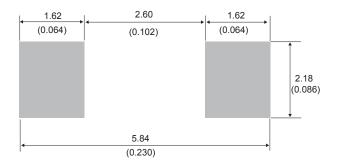
Table 6. SMB package mechanical data

	Dimensions					
Ref.	Millin	neters	Inches (for re	ference only)		
	Min.	Max.	Min.	Max.		
A1	1.90	2.45	0.074	0.097		
A2	0.05	0.20	0.001	0.008		
b	1.95	2.20	0.076	0.087		
С	0.15	0.40	0.005	0.016		
D	3.30	3.95	0.129	0.156		
E	5.10	5.60	0.200	0.221		
E1	4.05	4.60	0.159	0.182		
L	0.75	1.50	0.029	0.060		

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Figure 17. SMB recommended footprint



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3 Ordering Information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS160A	GA6	SMA	0.068 g	5000	Tape and reel
STPS160AFN	A160	SMA Flat Notch	0.039 g	10 000	Tape and reel
STPS160U	E16	SMB	0.107 g	2500	Tape and reel

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Revision history

Table 8. Document revision history

Date	Version	Changes
Jul-2003	6A	Last update.
Aug-2004	7	SMA package dimensions update. Reference A1 max changed from 2.70 mm (0.106 inc.) to 2.03 mm (0.080 inc).
16-Feb-2007	8	Reformatted to current standards. IF(RMS) removed from Table 2. Package dimensions and footprints updated. Ecopack statement added.
18-Mar-2010	9	Updated package illustration on page 1.
08-Oct-2019	10	Added Section 2.2 SMA Flat Notch package information.



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